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(12) **United States Design Patent**
Yoshida et al.

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(54) **SEAL MEMBER FOR SEMICONDUCTOR PRODUCTION APPARATUS**

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(**) Term: **15 Years**

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(22) Filed: **Sep. 21, 2020**

Related U.S. Application Data

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
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CPC C08K 5/0025; F16K 3/0227; F16K 51/02; F16J 15/062; F16J 15/025; F16J 15/3488
See application file for complete search history.

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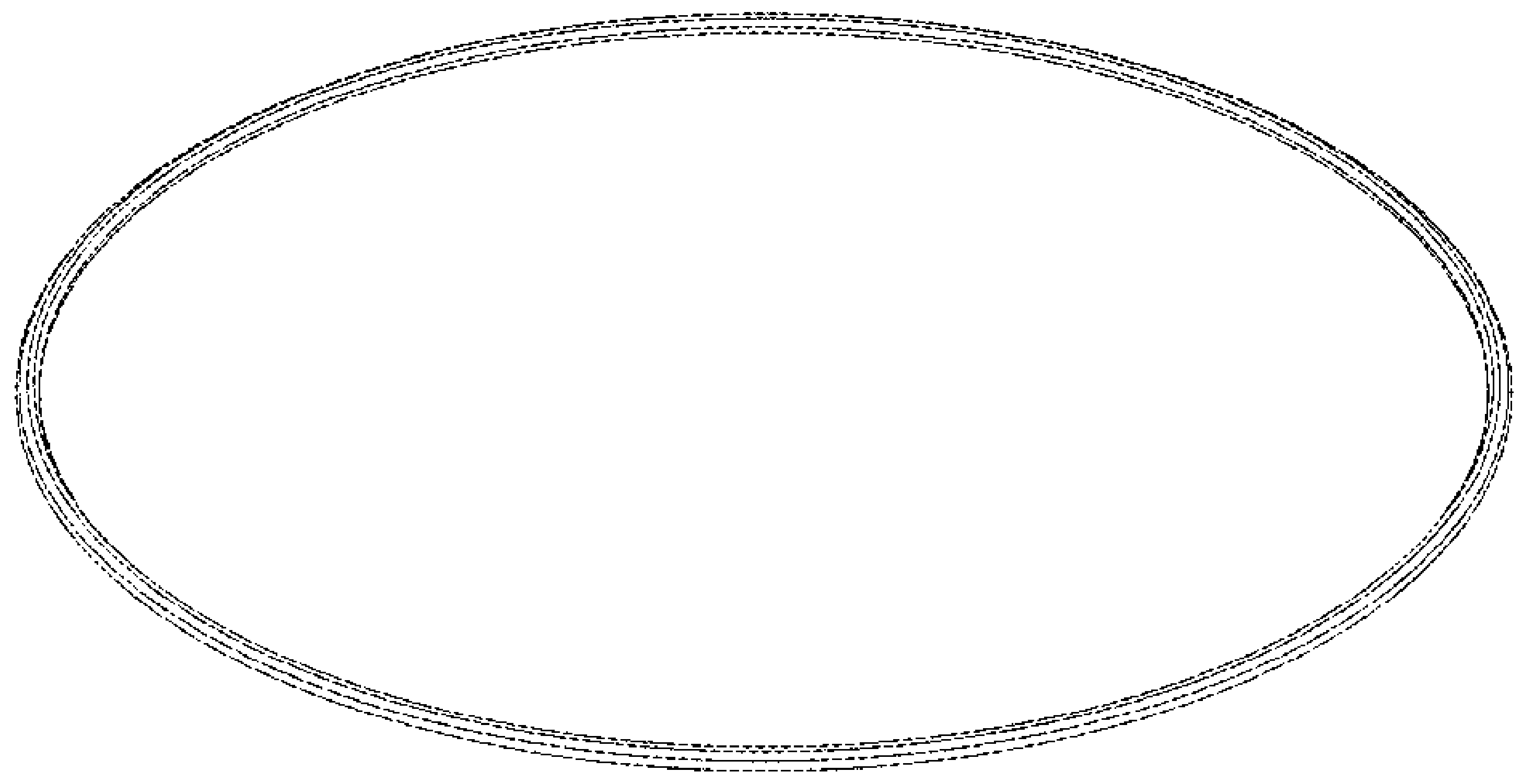
(57) **CLAIM**

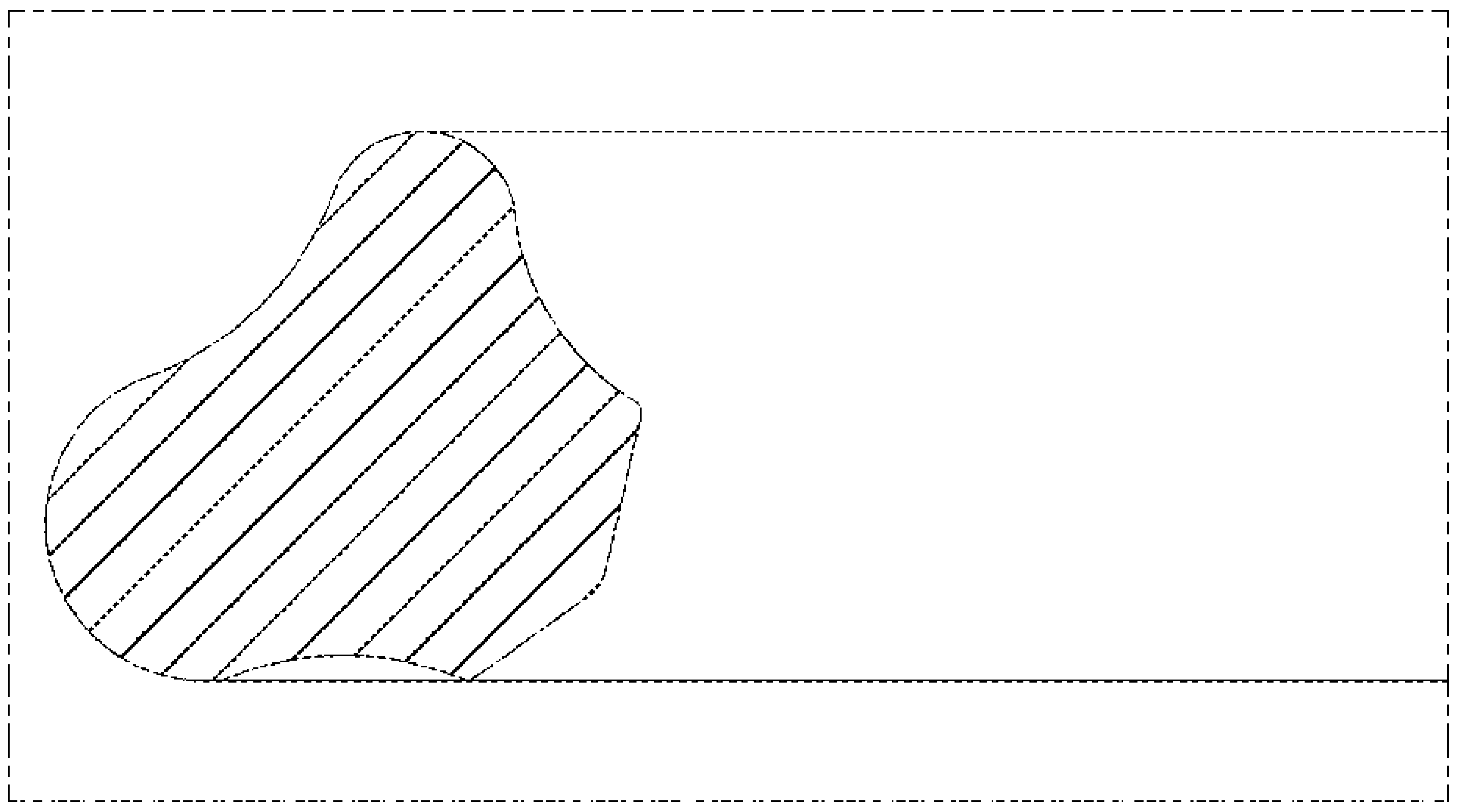
The ornamental design for a seal member for semiconductor production apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a seal member for semiconductor production apparatus, showing our new design;
FIG. **2** is a front elevation view thereof;
FIG. **3** is a rear elevation view thereof;
FIG. **4** is a left side elevation view thereof;
FIG. **5** is a right side elevation view thereof;
FIG. **6** is a top view thereof;
FIG. **7** is a bottom view thereof;
FIG. **8** is a cross-sectional view thereof taken along line **8-8** shown in FIG. **6**; and,
FIG. **9** is an enlarged cross-sectional view of a portion thereof taken from area **9-9** shown in FIG. **8**.

1 Claim, 9 Drawing Sheets





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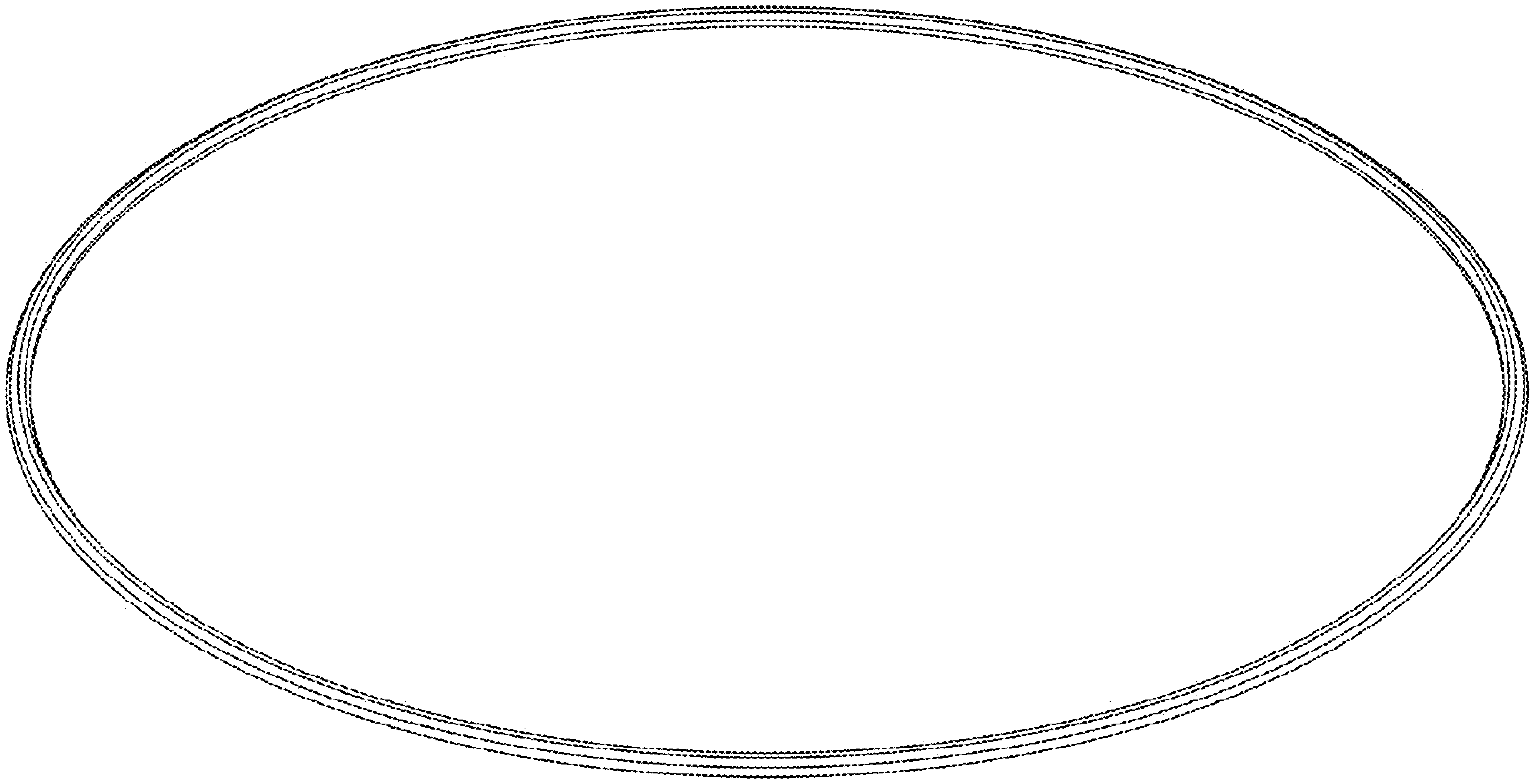

FIG. 1

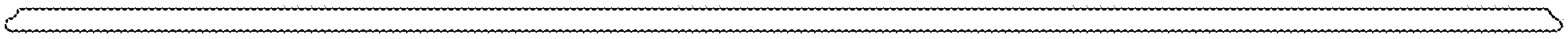

FIG. 2

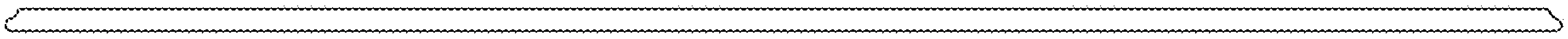

FIG. 3

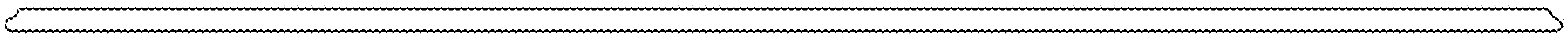

FIG. 4

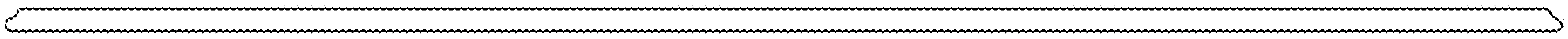

FIG. 5

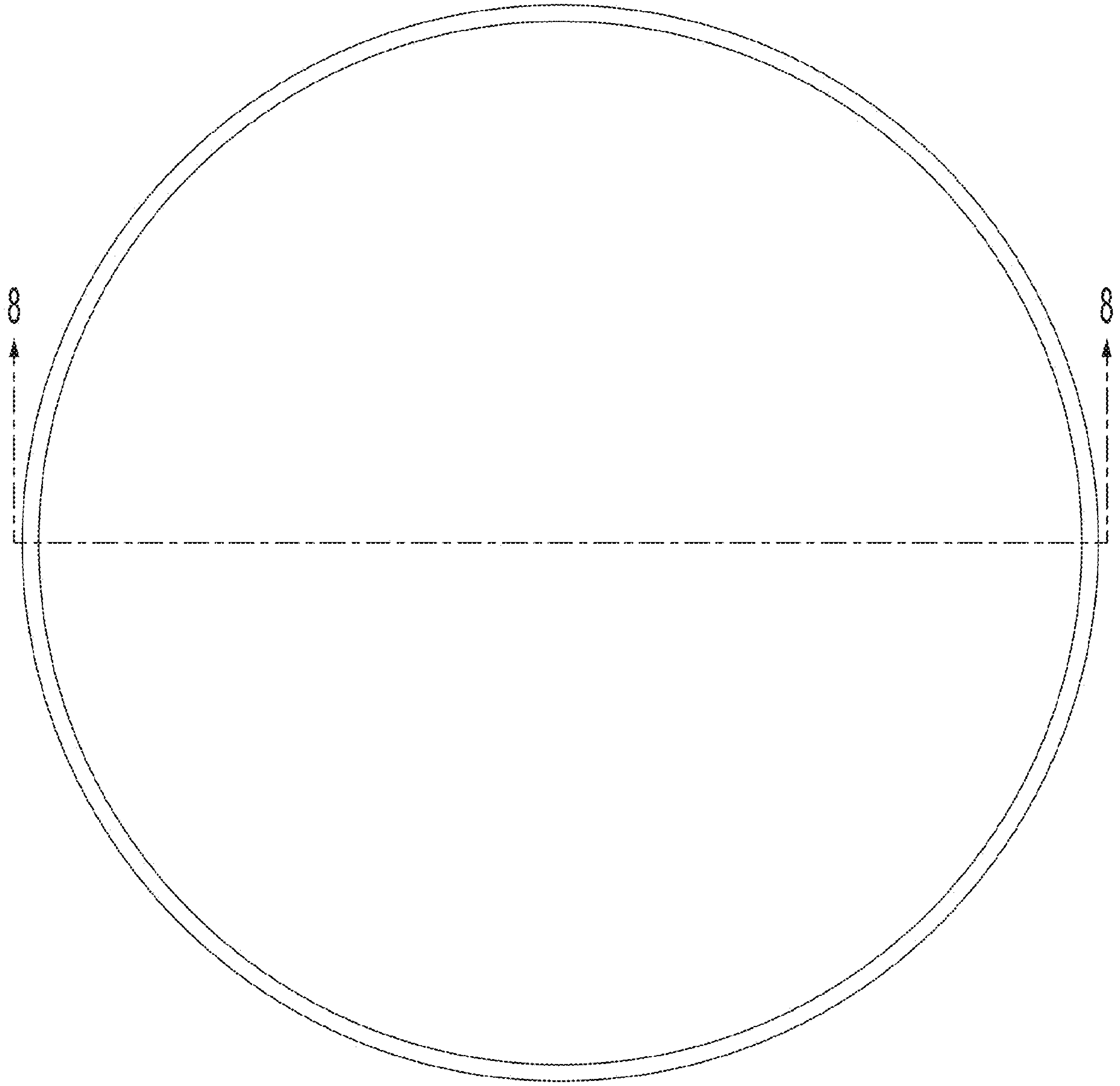

FIG. 6

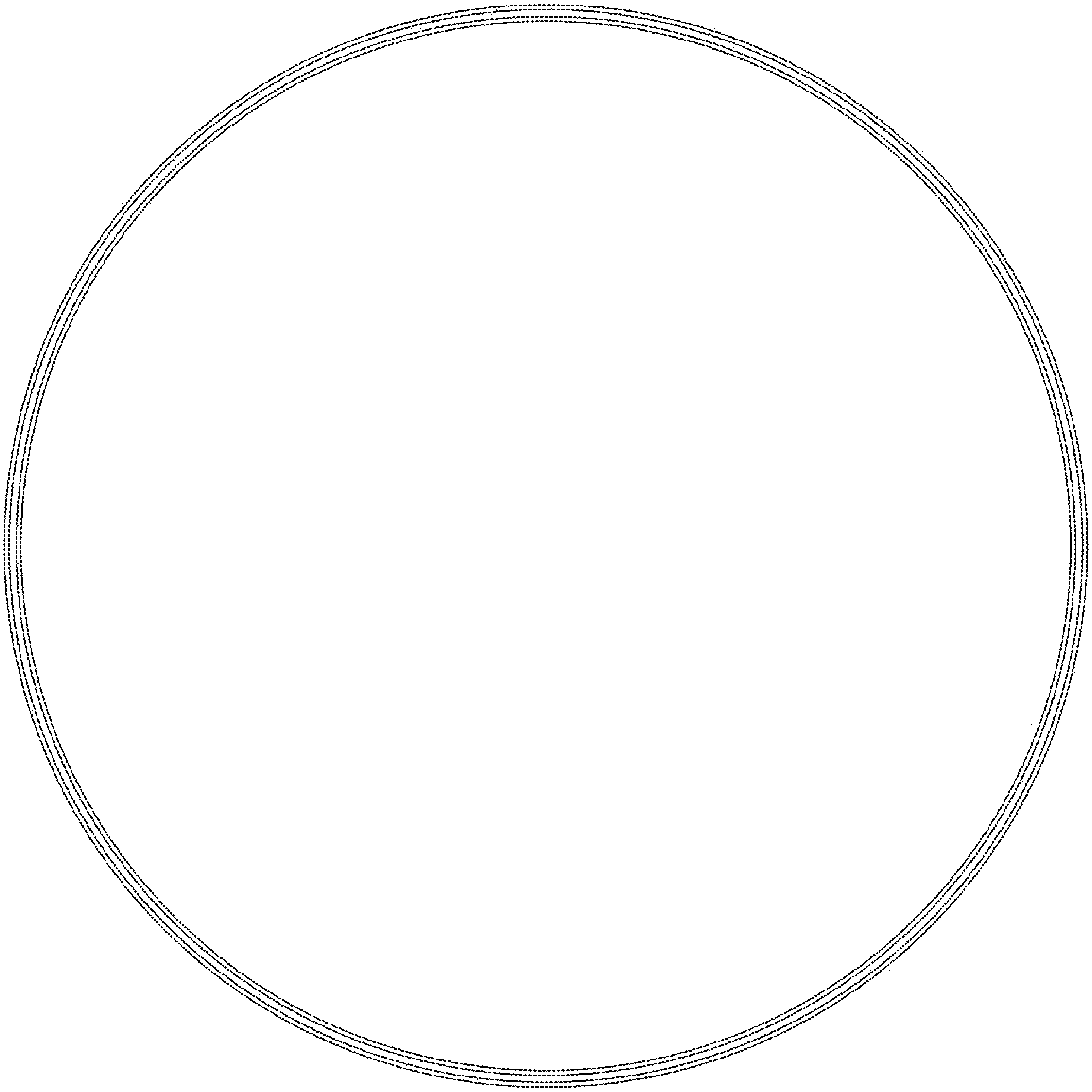

FIG. 7

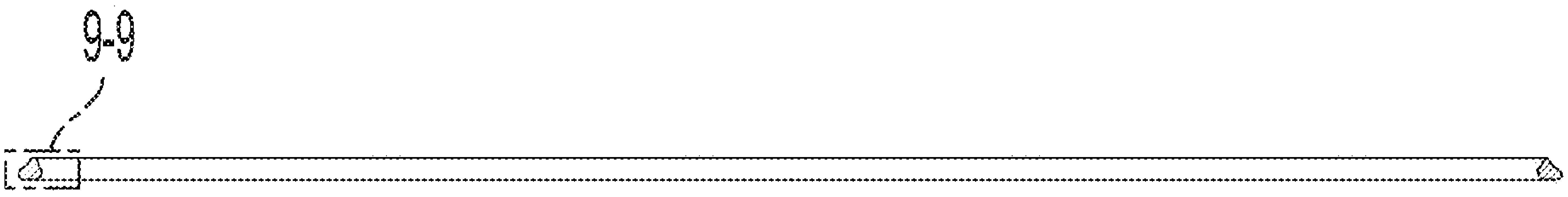

FIG. 8

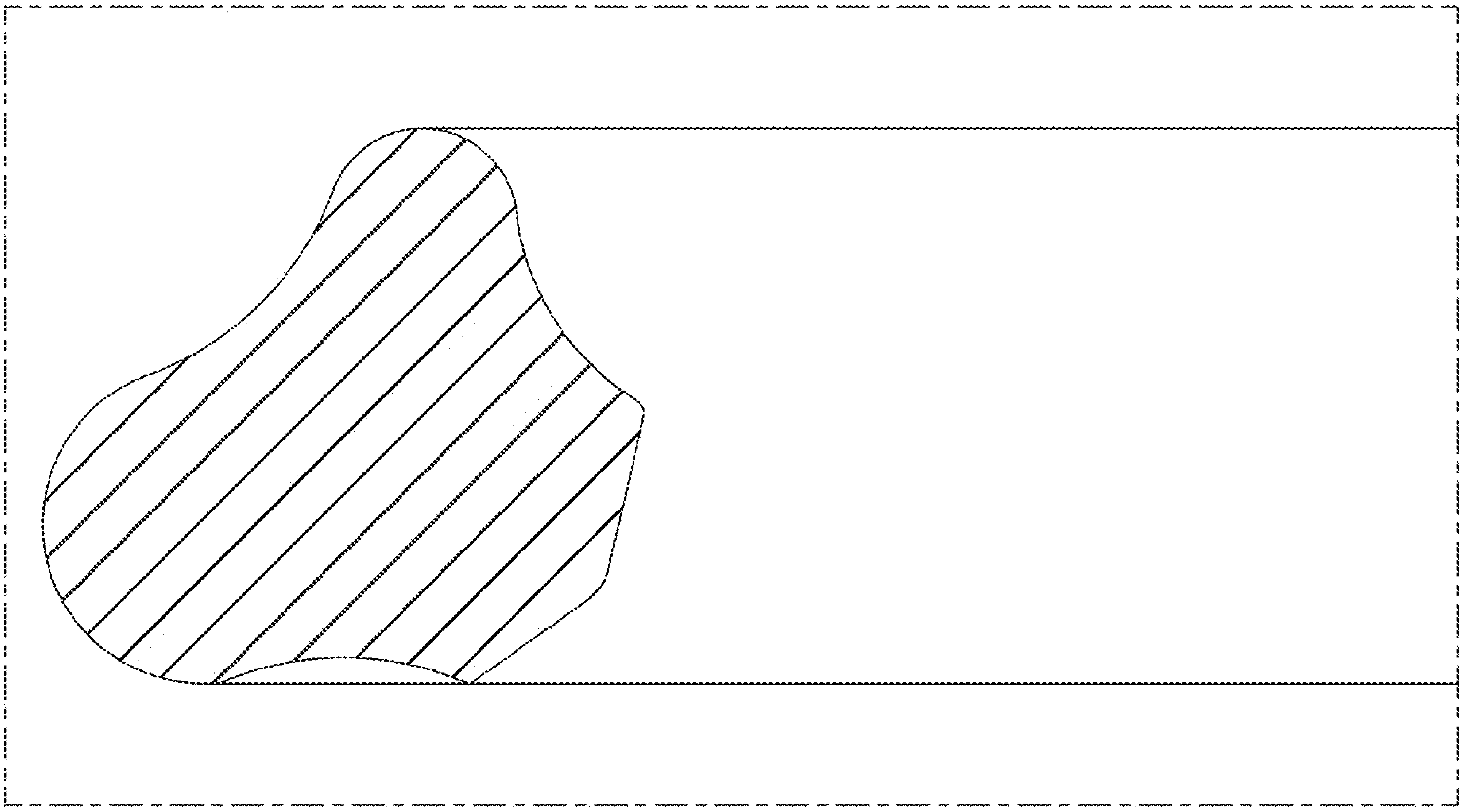

FIG. 9